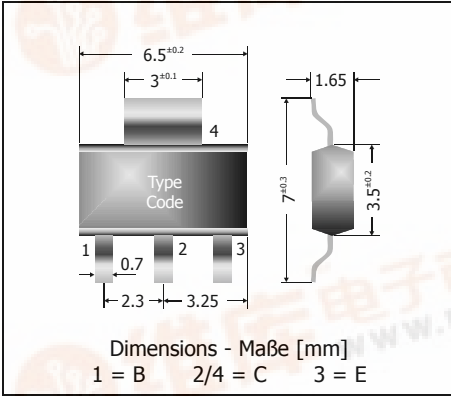


BCP51 ... BCP53

**BCP51 ... BCP53**  
**PNP Surface Mount General Purpose Si-Epi-Planar Transistors**  
**Si-Epi-Planar Universaltransistoren für die Oberflächenmontage PNP**

Version 2006-06-26



Power dissipation  
Verlustleistung 1.3 W

Plastic case  
Kunststoffgehäuse SOT-223

Weight approx.  
Gewicht ca. 0.04 g

Plastic material has UL classification 94V-0  
Gehäusematerial UL94V-0 klassifiziert

Standard packaging taped and reeled  
Standard Lieferform gegurtet auf Rolle



**Maximum ratings (T<sub>A</sub> = 25°C)**

**Grenzwerte (T<sub>A</sub> = 25°C)**

			BCP51	BCP52	BCP53
Collector-Emitter-volt. – Kollektor-Emitter-Spannung	B open	- V <sub>CEO</sub>	45 V	60 V	80 V
Collector-Base-voltage – Kollektor-Basis-Spannung	E open	- V <sub>CBO</sub>	45 V	60 V	100 V
Collector-Base-voltage – Kollektor-Basis-Spannung	C open	- V <sub>EBO</sub>	5 V		
Power dissipation – Verlustleistung		P <sub>tot</sub>	1.3 W <sup>1)</sup>		
Collector current – Kollektorstrom (dc)		- I <sub>C</sub>	1 A		
Peak Collector current – Kollektor-Spitzenstrom		- I <sub>CM</sub>	1.5 A		
Peak Base current – Basis-Spitzenstrom		- I <sub>BM</sub>	200 mA		
Junction temperature – Sperrschichttemperatur		T <sub>j</sub>	-55...+150°C		
Storage temperature – Lagerungstemperatur		T <sub>s</sub>	-55...+150°C		

**Characteristics (T<sub>j</sub> = 25°C)**

**Kennwerte (T<sub>j</sub> = 25°C)**

			Min.	Typ.	Max.
DC current gain – Kollektor-Basis-Stromverhältnis <sup>2)</sup>	- V <sub>CE</sub> = 2 V, - I <sub>C</sub> = 5 mA	all groups	h <sub>FE</sub>	25	
		Group -6	h <sub>FE</sub>	40	100
	- V <sub>CE</sub> = 2 V, - I <sub>C</sub> = 150 mA	Group -10	h <sub>FE</sub>	63	160
		Group -16	h <sub>FE</sub>	100	250
- V <sub>CE</sub> = 2 V, - I <sub>C</sub> = 500 mA	all groups	h <sub>FE</sub>	25	-	-
Collector-Emitter saturation voltage – Kollektor-Emitter-Sättigungsspg. <sup>2)</sup>	- I <sub>C</sub> = 500 mA, - I <sub>B</sub> = 50 mA	- V <sub>CEsat</sub>	-	-	0.5 V
		Base-Emitter voltage – Basis-Emitter-Spannung <sup>2)</sup>	- V <sub>BE</sub>	-	-

<sup>1)</sup> Mounted on P.C. board with 3 mm<sup>2</sup> copper pad at each terminal

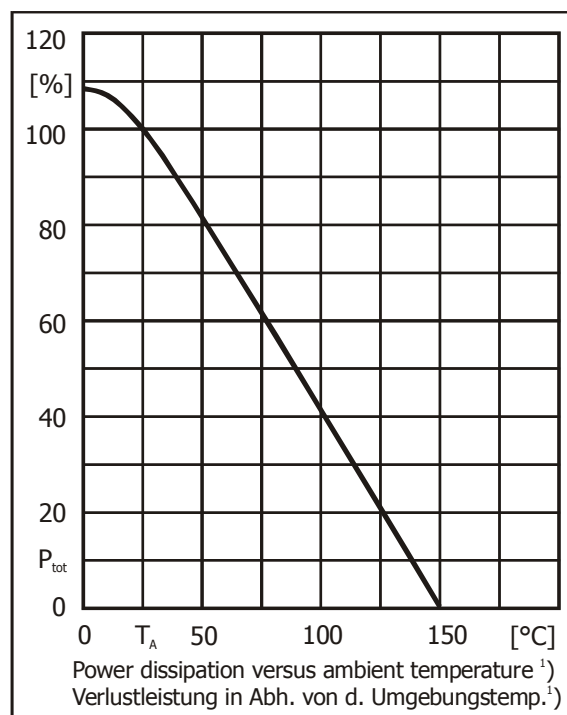
<sup>2)</sup> Montage auf Leiterplatte mit 3 mm<sup>2</sup> Kupferbelag (Lötpad) an jedem Anschluss

<sup>3)</sup> Tested with pulses t<sub>p</sub> = 300 μs, duty cycle ≤ 2% – Gemessen mit Impulsen t<sub>p</sub> = 300 μs, Schaltverhältnis ≤ 2%



**Characteristics ( $T_j = 25^\circ\text{C}$ )**
**Kennwerte ( $T_j = 25^\circ\text{C}$ )**

	Min.	Typ.	Max.
Collector-Base cutoff current – Kollektor-Basis-Reststrom			
- $V_{CB} = 30\text{ V}$ , (E open)	-	-	100 nA
- $V_{CB} = 30\text{ V}$ , $T_j = 125^\circ\text{C}$ , (E open)	-	-	10 $\mu\text{A}$
Emitter-Base cutoff current – Emitter-Basis-Reststrom			
- $V_{EB} = 5\text{ V}$ , (C open)	-	-	100 nA
Gain-Bandwidth Product – Transitfrequenz			
- $V_{CE} = 5\text{ V}$ , - $I_C = 10\text{ mA}$ , $f = 100\text{ MHz}$	-	120 MHz	-
DC current gain ratio of the complementary pairs Verhältnis der Stromverstärkungen komplementärer Paare			
$I_C$   = 150 mA,   $V_{CE}$   = 2 V	-	-	1.6
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft	$R_{thA}$	< 93 K/W <sup>1)</sup>	
Thermal resistance junction to soldering point Wärmewiderstand Sperrschicht – Lötpad	$R_{thS}$	< 27 K/W	
Recommended complementary NPN transistors Empfohlene komplementäre NPN-Transistoren	BCP54 ... BCP56		



1 Mounted on P.C. board with 3 mm<sup>2</sup> copper pad at each terminal  
 Montage auf Leiterplatte mit 3 mm<sup>2</sup> Kupferbelag (Lötpad) an jedem Anschluss